TOREX

Torex...Powerfully Small!

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XCL101xxxxBR-G
Typical Mass: 20 mg

Part	Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Coil	Core（Ferrite）	7.706	Iron oxide	385300	1309-37-1
		2.371	Zinc oxide	118600	1314-13-2
		1.304	Nickel oxide	65200	1313-99-1
		0.474	Copper oxide	23700	1317-38-0
	Base substrate	0.105	Bismaleimide triazine resin / Epoxy Resin	5300	-
		0.068	Inorganic filler	3400	-
		0.203	Fiberglass	10100	65997-17-3
	Overcoating Resin A	0.054	Epoxy resin	2700	25068-38-6
	(Inter layer)	0.121	Silica	6000	-
	Overcoating Resin B	0.043	Epoxy resin	2200	25068-38-6
	（Top coating）	0.096	Silica	4800	-
	Adhesive Resin	0.290	Epoxy resin	14500	25068-38-6
		0.646	Silica	32300	-
	Conductor	2.340	Copper	117000	7440-50-8
	Plating	0.043	Nickel	2200	7440-02-0
		0.118	Tin	5900	7440-31-5
Adhesive Resin	Adhesive Resin	0.012	Epoxy resin	600	-
		0.007	Silica	400	14808-60-7
IC	Silicon chip	0.340	Silicon	17000	7440-21-3
		-	Arsenic	<1	7440-38-2
	Lead-pad	1.255	Nickel	62800	7440-02-0
		0.116	Silver	5800	7440-22-4
		0.022	Gold	1100	7440-57-5
	Die attach	0.024	Epoxy resin	1200	-
		0.018	Silica	900	60676-86-0
	Bonding wire	0.071	Gold	3500	7440-57-5
	Resin	1.670	Silica	83500	60676-86-0
		0.170	Epoxy resin	8500	-
		0.159	Phenol resin	8000	-
		0.155	Metal hydroxide	7700	-

* The component composition is based on the information provided by raw material vender.
* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.
* Any indication "-" in CAS number means "confidential."